Name: TBA

BOM:

1: Smartphone

1: Infrared Sensor (MS Kinect); or

1: Ultrasonic Sensor

1: Headset Frame

1: Headset Circuit Board

1: In-ear headphones

1: Connector Cable

Design:

1. Depth information gathered by sensor, in Headset Circuit Board
2. Data is passed from headset to smartphone
3. Data is processed by smartphone,
4. Audio data sent from smartphone to user through headphones